

80V N-Channel Enhancement Mode MOSFET

Voltage

80 V

Current

155 A

Features

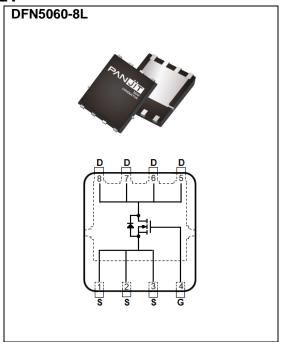
- RDS(ON), VGS@10V, ID@20A<3.3m Ω
- R_{DS(ON)}, V_{GS}@7V, I_D@10A<4mΩ
- Excellent FOM
- Standard Level Drive
- AEC-Q101 qualified
- Lead free in compliance with EU RoHS 2.0
- Green molding compound as per IEC 61249 standard

Mechanical Data

• Case: DFN5060-8L Package

• Terminals : Solderable per MIL-STD-750, Method 2026

• Approx. Weight: 0.08 grams



Maximum Ratings and Thermal Characteristics (T_A=25°C unless otherwise noted)

PARAMETER		SYMBOL	LIMIT	UNITS	
Drain-Source Voltage		V _{DS}	80	V	
Gate-Source Voltage		V _{GS}	±20		
Continuous Drain Current(Note 3)	T _C =25°C		155		
	T _C =100°C	I _D	110	Α	
Pulsed Drain Current(Note 1)	Tc=25°C	I _{DM}	620		
Power Dissipation	Tc=25°C	D-	160	W	
	T _C =100°C	Po	80		
Continuous Drain Current(Note 4)	T _A =25°C	I _D	22.5	А	
	T _A =70°C		18.8		
Power Dissipation	T _A =25°C	Do	3.3	W	
	T _A =70°C	Pb	2.3		
Single Pulse Avalanche Current(Note 5)		las	23	Α	
Single Pulse Avalanche Energy ^(Note 5)		Eas	235	mJ	
Operating Junction and Storage Temperature Range		T _J ,T _{STG}	-55~175	°C	
Thermal Resistance ^(Note 4)	Junction to Case	R _{θJC}	0.94	°C/W	
	Junction to Ambient	R _{θJA}	45		



Electrical Characteristics (T_A=25°C unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNITS	
Static							
Drain-Source Breakdown Voltage	BV _{DSS} V _{GS} =0V, I _D =250uA		80	-	-		
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250uA	2	3	4	V	
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} =10V, I _D =20A	ı	2.6	3.3		
		V _{GS} =7V, I _D =10A	- 3.1 4		mΩ		
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =80V, V _{GS} =0V	-	-	1	uA	
Gate-Source Leakage Current	I _{GSS}	V _{GS} =±20V, V _{DS} =0V	-	-	±100	nA	
Dynamic ^(Note 6)							
Total Gate Charge	Q_g	101/1	-	89	120	nC	
Gate-Source Charge	Q_{gs}	V _{DS} =40V, I _D =20A,	ı	18	-		
Gate-Drain Charge	Q_{gd}	V _{GS} =10V	-	21	-		
Input Capacitance	Ciss		-	5268	6900	pF	
Output Capacitance	Coss	V _{DS} =40V, V _{GS} =0V,	-	939	1400		
Reverse Transfer Capacitance	Crss	f=1MHz	ı	25	50		
Gate resistance	Rg	f=1MHz	-	1.3	-	Ω	
Turn-On Delay Time	td _(on)	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	-	21	-	ns	
Turn-On Rise Time	tr	V _{DS} =40V, I _D =20A,	-	23	-		
Turn-Off Delay Time	td _(off)	$V_{GS}=10V, R_{G}=3\Omega$ (Note 2)	-	60	-		
Turn-Off Fall Time	tf	(Note 2)	-	22	-		
Drain-Source Diode							
Diode Forward Current	Is	T _C =25°C	ı	-	155	A	
Pulsed Diode Forward Current	I _{SM}	(Package Limit)	-	-	620		
Diode Forward Voltage	V _{SD}	Is=20A, V _{GS} =0V	-	0.8	1.3	V	
Reverse Recovery Time	Trr	V _{DD} =40V,V _{GS} =0V,	-	64	-	ns	
Reverse Recovery Charge	Qrr	Is=20A,dIs/dt=100A/us	-	82	-	nC	

NOTES:

- 1. Pulse width<100us, Duty cycle<2%.
- 2. Essentially independent of operating temperature typical characteristics.
- 3. Chip capability with an $R_{\theta JC}$ =0.94°C/W, Package limited 120A.
- 4. R_{BJA} is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. Mounted on a 1 inch² with 2oz.square pad of copper.
- 5. Eas is calculated based on the condition of L=1mH, Ias=21.7A, V_{DD}=30V, V_{GS}=10V. 100% test at L=0.5mH, Ias=23A in production.
- 6. Guaranteed by design, not subject to production testing.

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TYPICAL CHARACTERISTIC CURVES

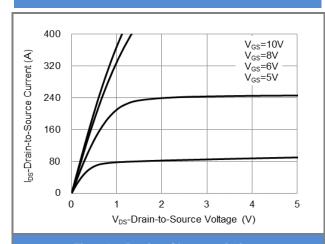


Fig.1 On-Region Characteristics

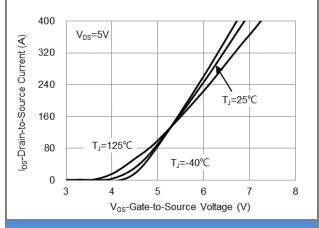


Fig.2 Transfer Characteristics

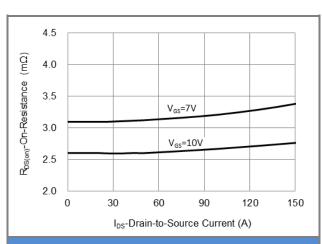


Fig.3 On-Resistance vs. Drain Current

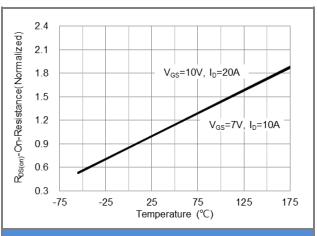
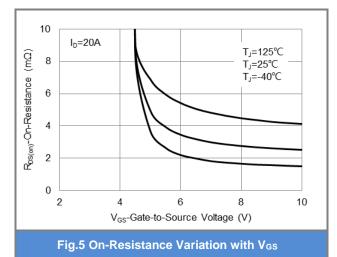
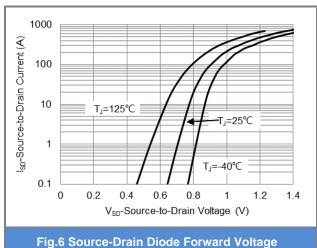


Fig.4 On-Resistance vs. Junction temperature





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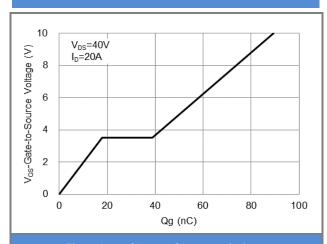


Fig.7 Gate-Charge Characteristics

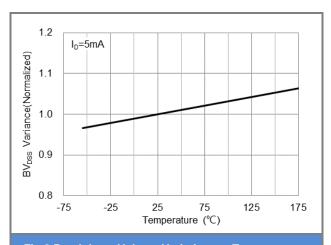


Fig.8 Breakdown Voltage Variation vs. Temperature

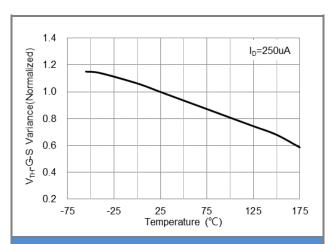


Fig.9 Threshold Voltage Variation with Temperature

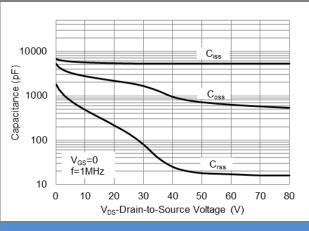
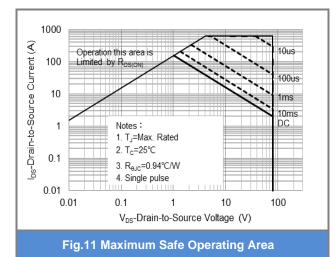


Fig.10 Capacitance vs. Drain-Source Voltage



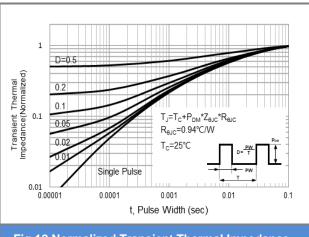


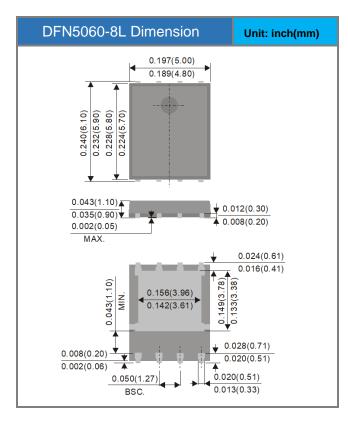
Fig.12 Normalized Transient Thermal Impedance

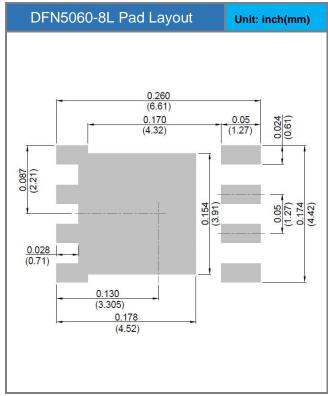


Product and Packing Information

Part No.	Package Type	Packing Type	Marking
PJQ55802-AU	DFN5060-8L	3K pcs / 13" reel	Q55802

Packaging Information & Mounting Pad Layout







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